

IN THE SPECIFICATION

Page 4, lines 15-18 - Please replace this paragraph with the following amended paragraph:

If conductive vias are used, it is contemplated that such vias will comprise a solder paste rather than a transient liquid phase sintered material. Preferred solder pastes include PbSn, PbSnAg, Indium alloys, and Au eutectic/alloys, if wire piercing/thermosonic ball formation is used.[.] As used herein, the phrase “solder paste” means a composition that comprises a metal or alloy powder, a rosin compound, a rheological additive, a solvent or solvent mixture, a surfactant or surfactant mixture, and/or a buffer or neutralizing agent.